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COOL-PAD

CPR7158

Tacky
Non-curing
Compressible Thermal Pad
Flexible From -60 to150ºC

IDEAL FOR:

- **Thermal Grease Replacement**
- **Thermal Gasket Replacement**
- **Gap Filling**

DESCRIPTION:

CPR7158 is an aluminum nitride crystallite filled, electrically insulating, thermal interface material for gap filling applicaton. It is designed to have high compressibility and enhance thermal transfer from power device to heat-sink.

UL94V-0 Rating

TYPICAL PROPERTIES*

Electrical Resistivity (25 ºC/ As is)	**>1x10 ^{13} ohm-cm**
Dielectric Strength (Volts/mil)	**>300V/mil**
Glass Transition Temp.(ºC)	**-60 ±10%**
Lap-Shear Strength	**N/A**
Device Push-off Strength	**N/A**
Hardness (Type)	**<50 (A)**
Cured Density (gm/cc)	**>2.5**
Thermal Conductivity	**>21 Btu-in/hr-ft²-ºF** **>3.0 W/m-ºC**
Linear Thermal Expansion Coeff. (ppm/ºC)	**160 ±15%**
Maximum Continuous Operation Temp. (ºC)	**<150**

* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

AVAILABILITY:

CPR7158 is available in sheet sizes, reel, and as custom preforms of 3 and 6 mils. Standard thicknesses also include 0.010", 0.020" and 0.040" for gap-filling applications. Special thicknesses are available.

APPLICATION PROCEDURES:

(1) Cut or pre-cut to desired size and shape.

(2) Place COOL-PAD between device and heatspreader or heat-sink.

(3) Clamp with >5 psi for optimum conformance.

(4) The temperature at which the phase changes is 60ºC.

Usage Conditions

Temperature	Time	Pressure
Ambient	As is	>5 psi

SHELF LIFE:

Storage temperature	Shelf Life
25ºC	1 yr

in original sealed package

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details.